

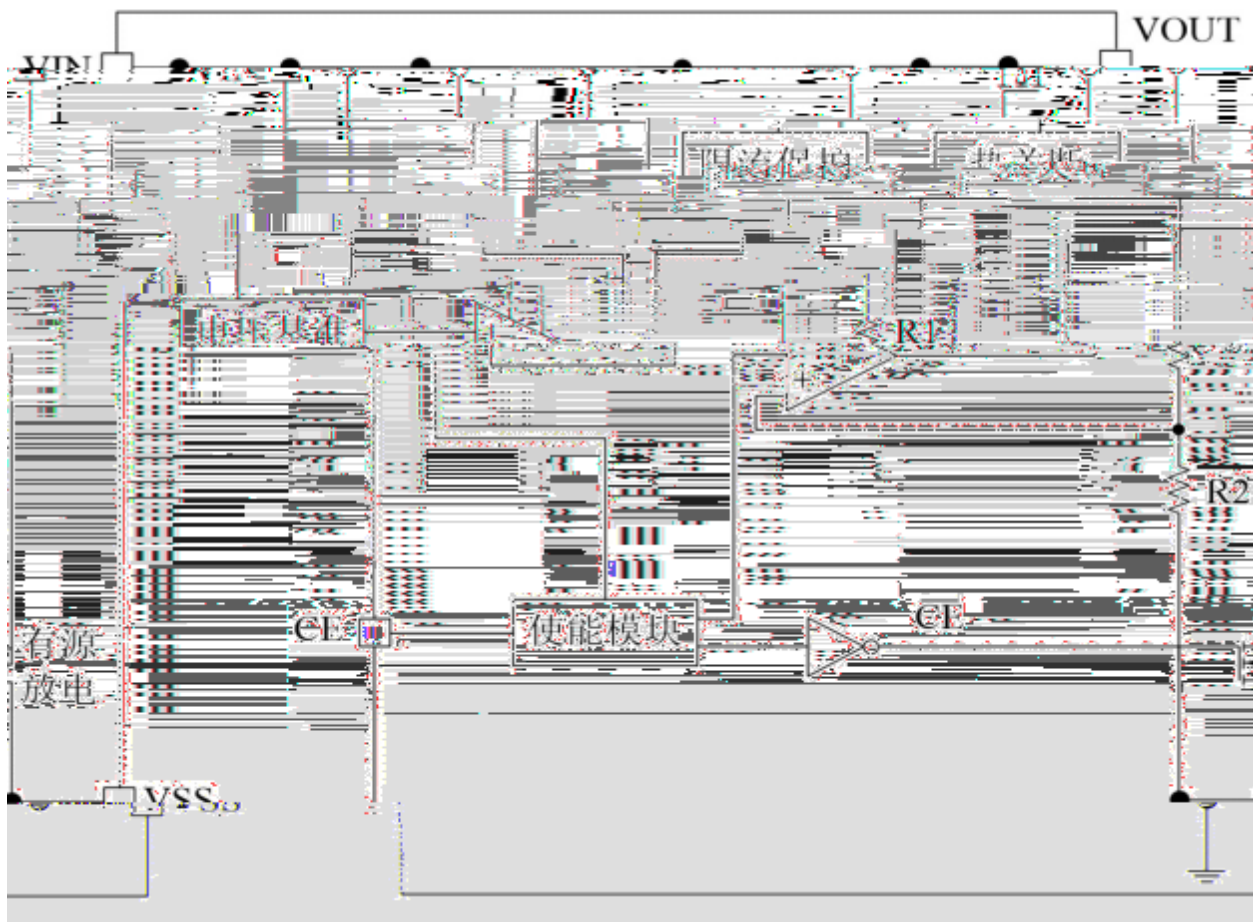
/ Absolute Maximum Ratings(Ta=25)

	V _{IN_MAX}	30	V
	V _{IN}	-0.3~30	V
CE	V _{CE}	V _{IN} -0.3~V _{IN} +0.3	V
	I _{OUT}	0~500	mA
	P _D	0.3	W
	T _{stg}	-40 to +150	°C
	T _{OP}	-40 to +85	

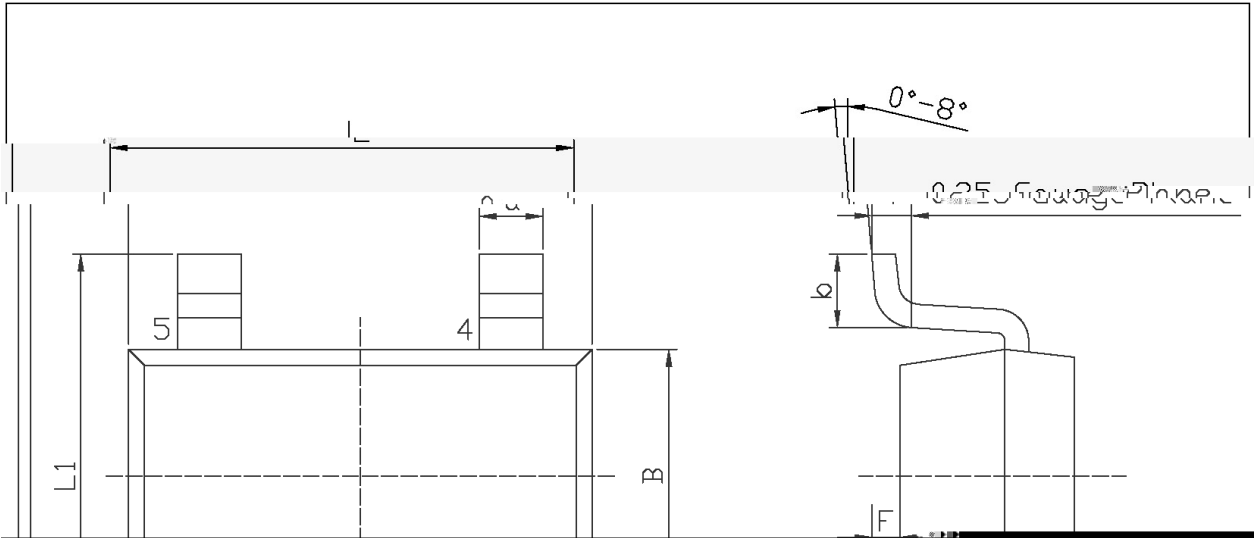
/ Electrical Characteristics(T_A=25 , V_{IN}=V_{OUT}+1V, C_{IN}=C_{OUT}=1uF, unless otherwise specified)

	V _{IN}		2.5		24	V
	V _{OUT}	I _{OUT} =10mA	V _{OUT} *0.98		V _{OUT} *1.02	V
	I _{SS}	I _{OUT} =0mA	-	2.5	6	uA
	I _{ST}	CE=0V			0.2	uA
	L _{LIM}	-	500			mA
	V _{DROP}	I _{OUT} =100mA	-	200	-	mV
	I _{SHORT}			55		mA
	V _{CE_L}				0.4	V
	V _{CE_H}		1.5			V
	R _{DIS}	V _{CE} 0.4V		350		
	V _{LOAD}	V _{IN} =V _{OUT} +1 1mA I _{OUT} 100mA	-	5	20	mV
	V _{LINE}	I _{OUT} =10mA V _{OUT} +1V V _{IN} 20V	-	0.05	-	%/V
	V _{OUT} / (T _A *V _{OUT})	I _{OUT} =1mA -40 T _A +85	-	50	-	ppm/
	PSRR	V _{IN} =4.3V	f=100Hz	-	80	-
		V _{OUT} =3.3V	f=1kHz	-	65	-
		I _{OUT} =10mA	f=10kHz	-	50	-
	T _{SD}			-	160	-
	T _{SD}			-	25	-

/ Functionl Block Diagram

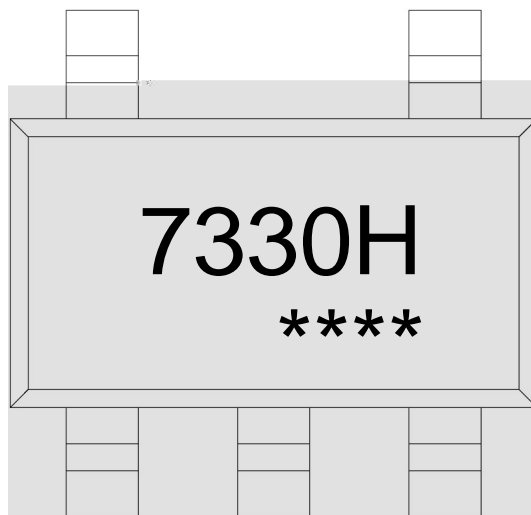


/ Package Dimensions



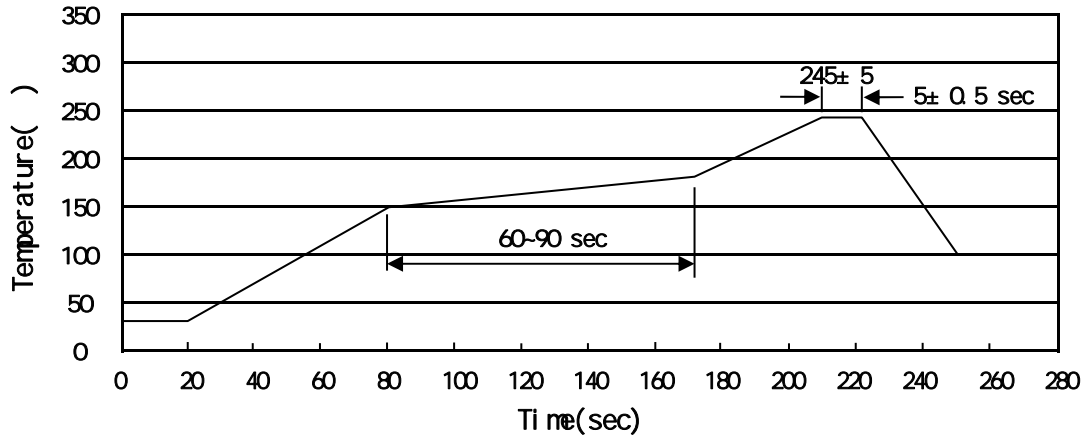
Symbol	Dimensions in Millimeters		Symbol	Dimensions in Millimeters	
	Min	Max		Min	Max
L	2.82	3.02	E1	0.85	1.05
B	1.50	1.70	a	0.35	0.50
C	0.90	1.30	c	0.10	0.20

/ Marking Instructions



7330H

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|-------|----------|---|
| 1 | 150 | 180 | 60 | 90sec; | 1.Preheating:150~180 , Time:60~90sec. |
| 2 | 245±5 | | 5±0.5 | sec; | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 | | | 2 | 10 /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm ³)		
	Units/Reel	Reels/Inner Box	Units/Inner Box	Inner Boxes/Outer Box	Units/Outer Box	Reel	Inner Box	Outer Box
SOT23-5/6	3,000	10	30,000	4	120,000	7 x8	210x205x205	445x435x230

/ Notices

All information provided in this document is subject to legal disclaimers.